SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SECK03

Super Bright Orange

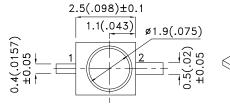
Features

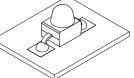
- Subminiature package.
- Gull wing lead.
- Long life solid state reliability.
- Low package profile.
- Moisture sensitivity level : level 3.
- Package : 1000pcs / reel.
- RoHS compliant.

Description

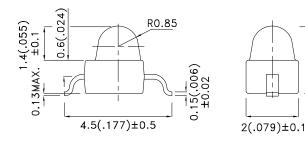
The Super Bright Orange device is made with AlGaInP (on GaAs substrate) light emitting diode chip.

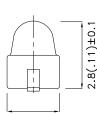
Package Dimensions





10 -17--0 2





Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide										
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]					
			Min.	Тур.	201/2					
AM2520SECK03	Super Bright Orange (AlGaInP)	WATER CLEAR	900	1800	20°					

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Orange	610		nm	l⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Orange	601		nm	l⊧=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Orange	29		nm	l⊧=20mA
С	Capacitance	Super Bright Orange	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Orange	2.1	2.5	V	l⊧=20mA
lr	Reverse Current	Super Bright Orange		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

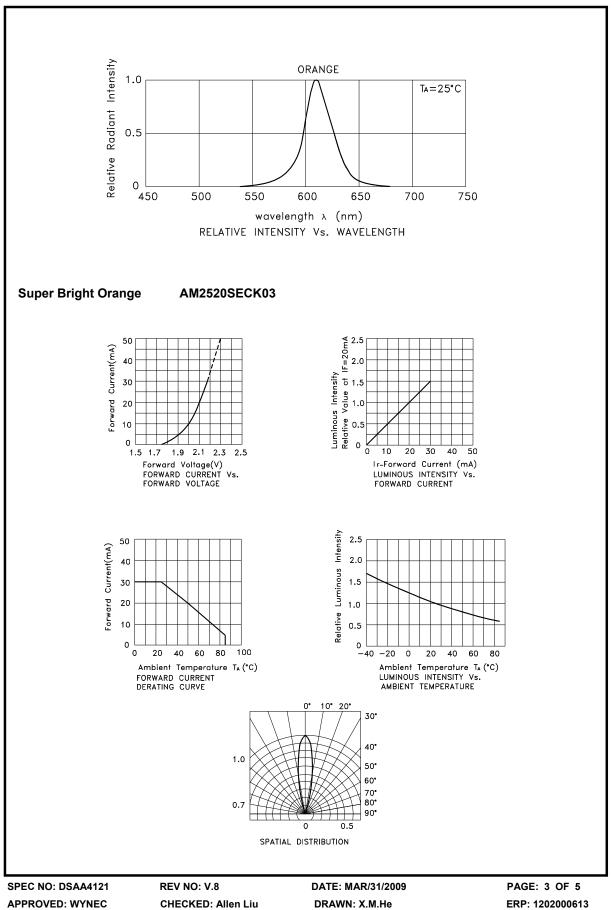
Parameter	Super Bright Orange	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	195	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process. 300 (°C) 10 s max 260°C max 250 230°C 4°C/s 4°C/s max 200 150~180°<u>C</u> 4°C/s 150 Temperature 60~120 30~50s 100 50 25°C 0 0 50 100 150 200 250 300 (sec) Time Time _____ NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature. 3.Number of reflow process shall be 2 times or less. Recommended **Soldering Pattern** 1.5 1.6 3.0 1.6 **Tape Dimensions** (Units : mm) TAPE 4.0±0.05 1.75±0.1 2±0.05 4.0±0.1 ø1.5 +0.1 0.3±0.05 3.05±0.1 5.5 ± 0.05 5 MAX. 12±0.2 5.3±0.1 5'MAX. Å 2.7±0.1 5'MAX. 5 MAX. 0.8±0.1 2.2±0.1 A-A SECTION

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